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Mahneke

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[54] METHOD AND APPARATUS FOR SPIN-COATING CHEMICALS

62-185321 8/1987 Japan .

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[57]

ABSTRACT

Disclosed is an apparatus and a method for spin coating chemicals over a surface of a substrate. The apparatus includes a bowl for supporting a substrate, the bowl has a plurality of drain holes defined below the level of the substrate. The apparatus further includes a lid having a flat surface configured to lie a predetermined distance above the substrate and mate with the bowl. Further, a plurality of injection holes defined in the bowl for applying a solvent to an underside of the substrate are included. The plurality of injection holes are defined in along an injection ring that is configured to receive the liquid solvent that is to be applied near an outer radius of the underside of the substrate, and the injection ring is spaced apart from the underside of the substrate.

26 Claims, 9 Drawing Sheets

